

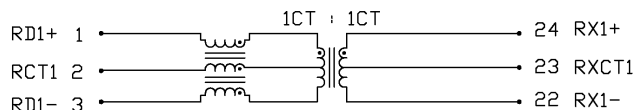
THE INFORMATION CONTAINED HEREIN IS CONSIDERED
"PROPRIETARY" TO BEL FUSE INC. AND SHALL NOT BE
COPIED, REPRODUCED OR DISCLOSED WITHOUT THE
WRITTEN APPROVAL OF BEL FUSE INC.



CHIP SIDE

MEDIA SIDE

ELECTRICAL CHARACTERISTICS (<25°C)



URNS RATIO

Rx CHIP SIDE: MEDIA SIDE
Tx CHIP SIDE: MEDIA SIDE

1CT : 1CT
1CT : 1CT

OCL

MEDIA SIDE

350μH MIN.
@ 100kHz, 100mVrms
w/8mA DC BIAS

INSERTION LOSS

100kHz
1MHz TO 100MHz
125MHz

1.2 dB MAX
1.0 dB MAX
3.0 dB MAX

RETURN LOSS

1MHz-30MHz
30MHz-80MHz
100MHz

18 dB MIN
12-20LOG<F/80MHz> dB MIN
10 dB MIN

CROSSTALK

1MHz
10MHz-100MHz

55 dB MIN
55-24LOG<F/10MHz> dB MIN

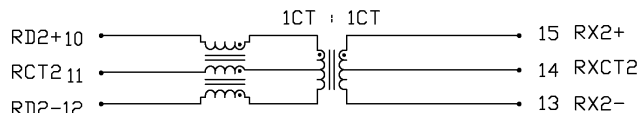
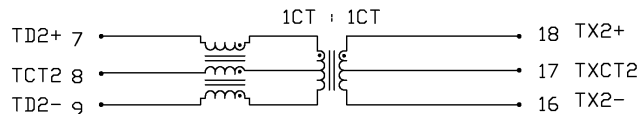
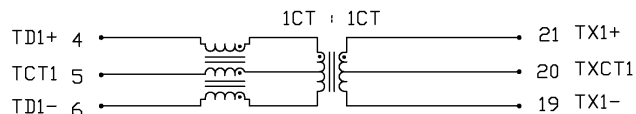
DM TO CM REJECTION

2MHz
30MHz - 200MHz

60 dB MIN
40-22LOG<F/30MHz> dB MIN

HIPOT

PER HAND-WORK-03



NOTES:

- THIS DESIGN CAN BE APPLIED TO EITHER 10/100 BASE T OR
1000 BASE T IF DESIRE.

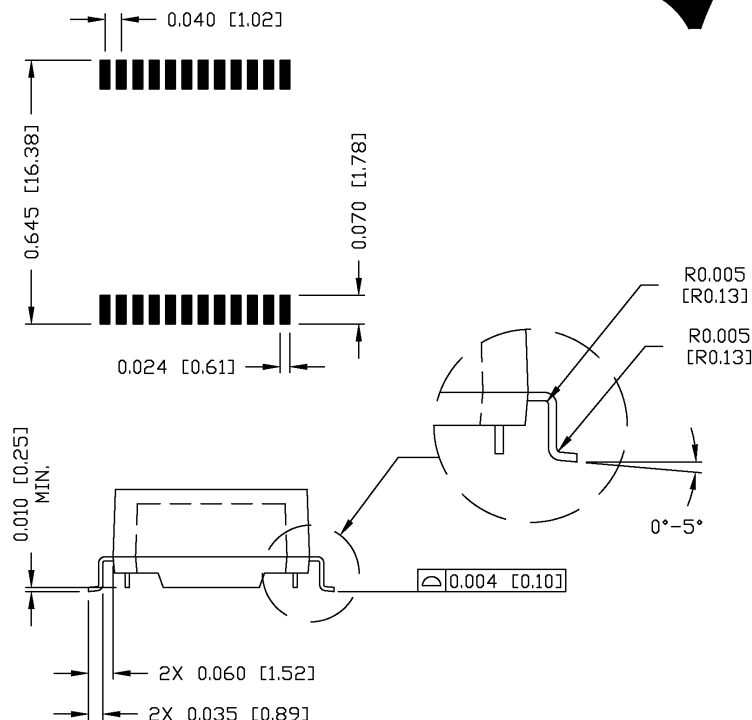
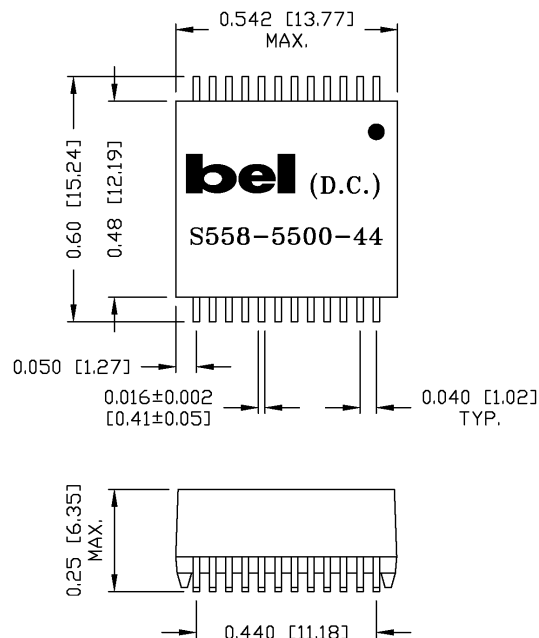
ORIGINATED BY	DATE	TITLE	PART NO. / DRAWING NO.	STANDARD DIM.	[] METRIC DIM. AS REFERENCE	
HO	10-26-05	ELECTRICAL SPECIFICATION	X558-5500-44	TOL. IN INCH	UNIT : INCH [mm]	REV. : A
DRAWN BY	DATE		FILE NAME	.X	SCALE : N/A	SIZE : A4
DQ Chen	10-26-05		X558550044A.DWG	.XX		PAGE : 2
				.XXX		

THE INFORMATION CONTAINED HEREIN IS CONSIDERED
 "PROPRIETARY" TO BEL FUSE INC. AND SHALL NOT BE
 COPIED, REPRODUCED OR DISCLOSED WITHOUT THE
 WRITTEN APPROVAL OF BEL FUSE INC.

RoHS
 2002/95/EC



SUGGESTED PCB PAD LAYOUT



NOTES:

1. STANDARD MARKING REFER TO DOC. HAND-WORK-04.
2. PACKAGE CODE: "QSS001".

ORIGINATED BY	DATE	TITLE	PART NO. / DRAWING NO.	STANDARD DIM.	[] METRIC DIM. AS REFERENCE	
HD	10-26-05	MECHANICAL DRAWING S558-5500-44	X558-5500-44	TOL. IN INCH	UNIT : INCH [mm]	REV. : A
DRAWN BY	DATE		FILE NAME	.X	SCALE : N/A	SIZE : A4
DQ Chen	10-26-05		X558550044A.DWG	.XX ±0.01 .XXX ±0.005	SCALE : N/A	PAGE : 3

